

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	253	(semiconductor or die or dice or chip or IC) and capacitor same ("SiC" or silicon near carbide) and (via or hole or plug or interconnect\$3) with ("Si" or silicon or silicide or silicone)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/21 22:54
L3	110	(semiconductor or die or dice or chip or IC) and capacitor same (dielectric or insulat\$3) with ("SiC" or silicon near carbide) and (via or hole or plug or interconnect\$3) with ("Si" or silicon or silicide or silicone)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/21 22:55
L4	84	(semiconductor or die or dice or chip or IC) and capacitor with ("SiC" or silicon near carbide) and (via or hole or plug or interconnect\$3) with ("Si" or silicon or silicide or silicone)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/21 22:55
L5	66	3 not 4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/21 23:07
L6	143	2 not 3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/21 23:09
L7	909	257/754	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/21 23:37
L8	317	257/756	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/21 23:37